

GP120R75T4

N-channel 1200V 20A GaN Power HEMT in TO247-4 Package

Preliminary Datasheet version: 1.2

Features

BV_{dss}	R_{dson}	I_{ds}	V_{GS}	$V_{GS(TH)}$
1200V	75m Ω	20A	-20 V to 20V	2.7 V

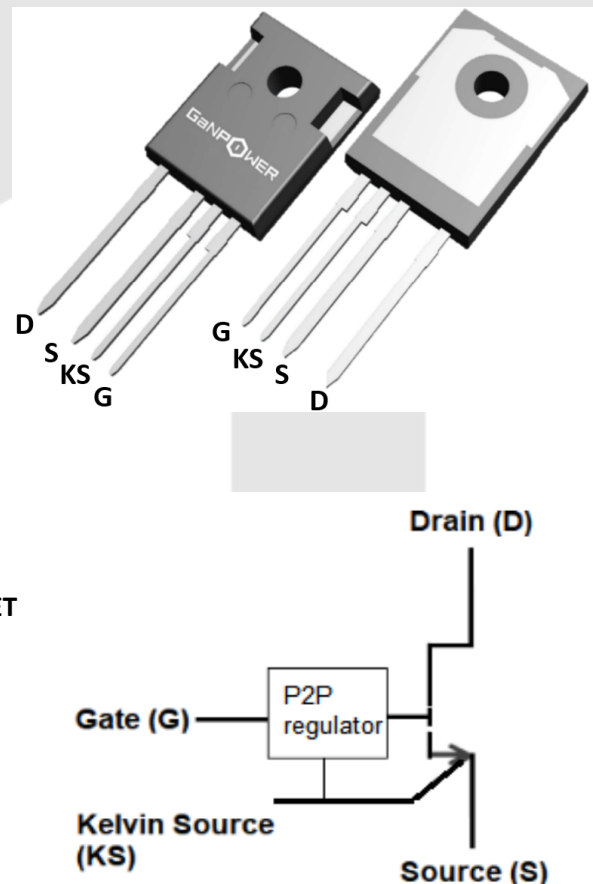
- Ultra-low R_{dson}
- High dv/dt capability
- Extremely low input capacitance
- Zero Qrr
- Outstanding switching performance
- Low Profile
- Upgraded P2P GaN with input regulator IC to match input lead and voltage of existing SiC MOSFET

Applications

- Switching Power Applications
- Server and Telecom Power Application
- EV OBC and DC-DC Converters UPS, Inverters, PV

Description

These devices are N-channel 1200V Power GaN HEMTs based on proprietary E-mode GaN on silicon technology, integrating an input regulator circuit to match input lead and voltage of existing SiC MOSFET in a pin-to-pin (P2P) fashion. The resulting product has extremely low on-state resistance, very low input capacitance and zero reverse recovery charge, making it especially suitable for applications which require superior power density, ultra-high switching frequency and outstanding efficiency.





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Device Characteristics

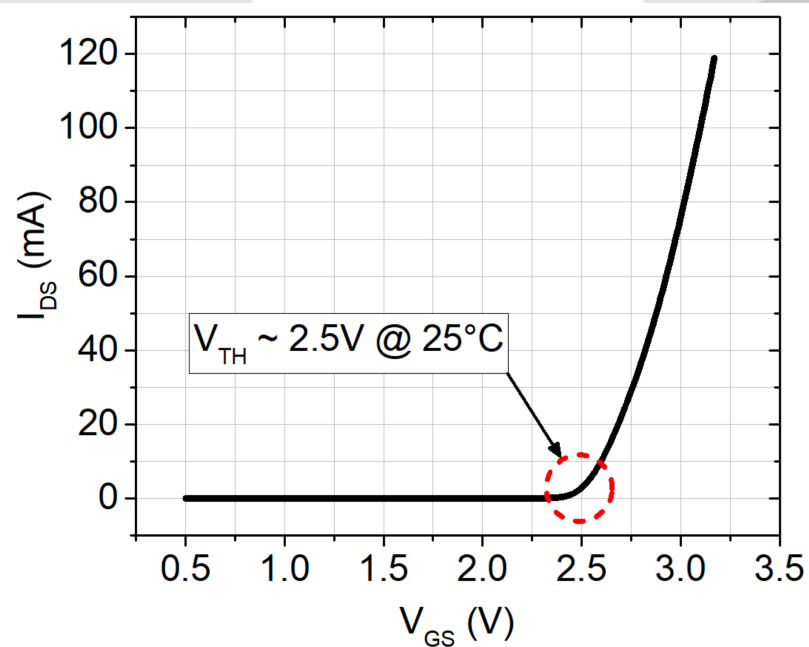
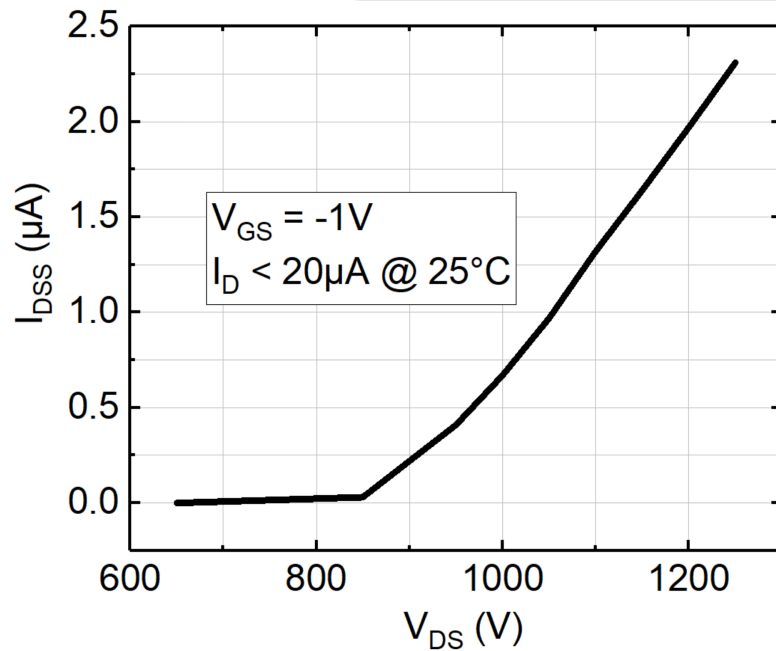
Basic Parameters				Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
1	$V_{GS(TH)}$	Zero gate voltage drain current, $T_c = 25^\circ\text{C}$	$V_{DS} = V_{GS}$ $I_D = 3\text{mA}$	2.5	2.7	2.9	V
2	V_G	Gate voltage range		-20	12	20	V
3	BV_{DSS}	Drain-Source breakdown voltage	$V_{GS} = 0\text{V}$ $I_D < 20\mu\text{A}$		1200		V
4	I_{DSS}	Zero gate voltage drain current, $T_c = 25^\circ\text{C}$	$V_{GS} = 0\text{V}$ $V_{DS} = 1200\text{V}$	1.0	2.5	4.0	μA
5	I_{GSS}	Gate-Source Leakage @ 25°C	$V_{GS} = 12\text{V}$ $V_{DS} = 0\text{V}$	30	50	80	mA
6	$R_{DS(on)}$	Static drain-source on resistance, $T_c = 25^\circ\text{C}$	$V_{GS} = 12\text{V}$	70	75	85	m Ω
Switching Performance				Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
1	$t_{D(ON)}$	Turn-on delay time	$V_{DS} = 800\text{V}$ $I_D = 9\text{A}$ $V_{GS} = +12\text{V}/-1\text{V}$ $R_{GON} = 2\Omega$ $R_{GOFF} = 0\Omega$		21		ns
2	t_R	Rise time			38		ns
3	$t_{D(OFF)}$	Turn-off delay time			11		ns
4	t_F	Fall time			24		ns



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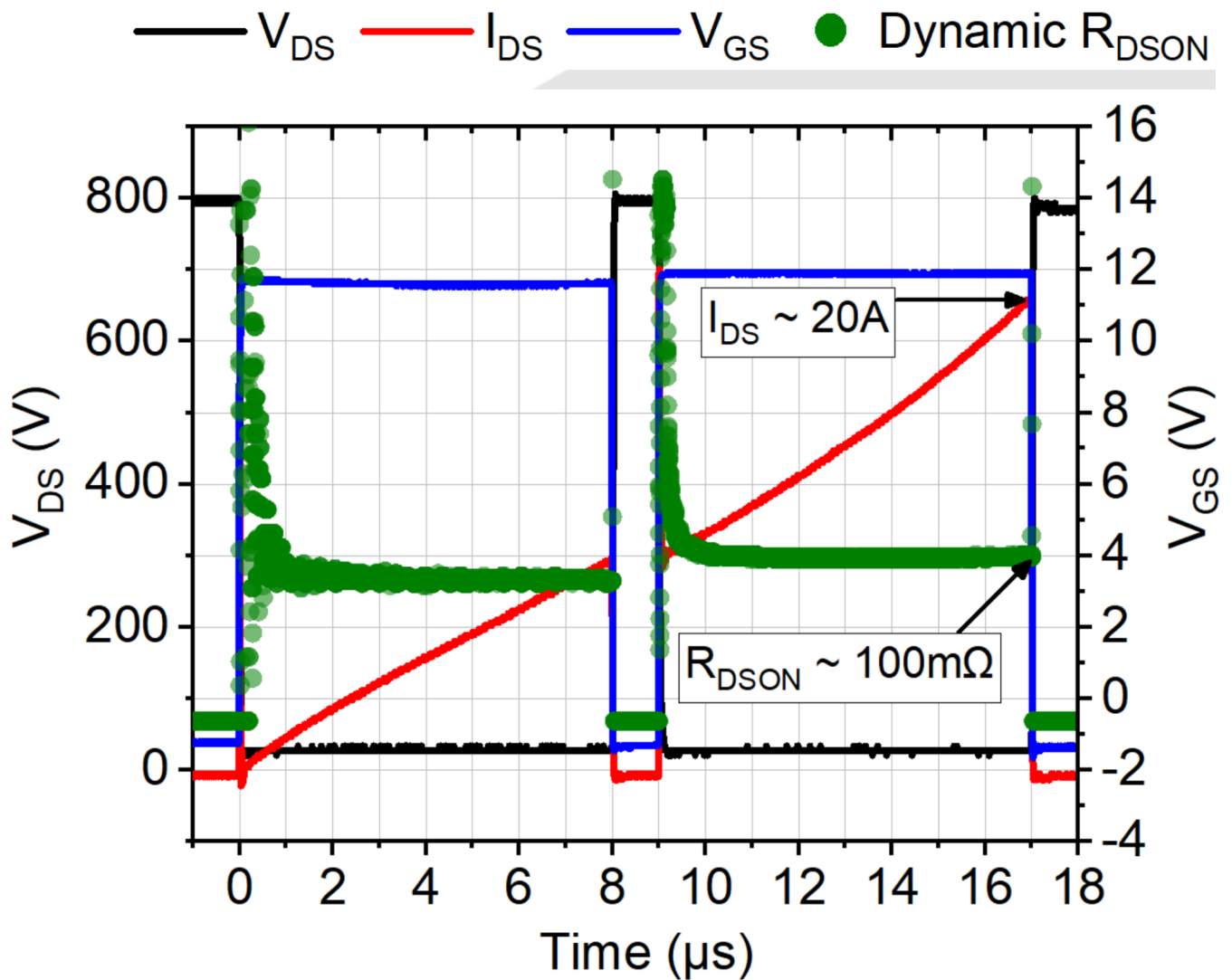
Electrical Performance





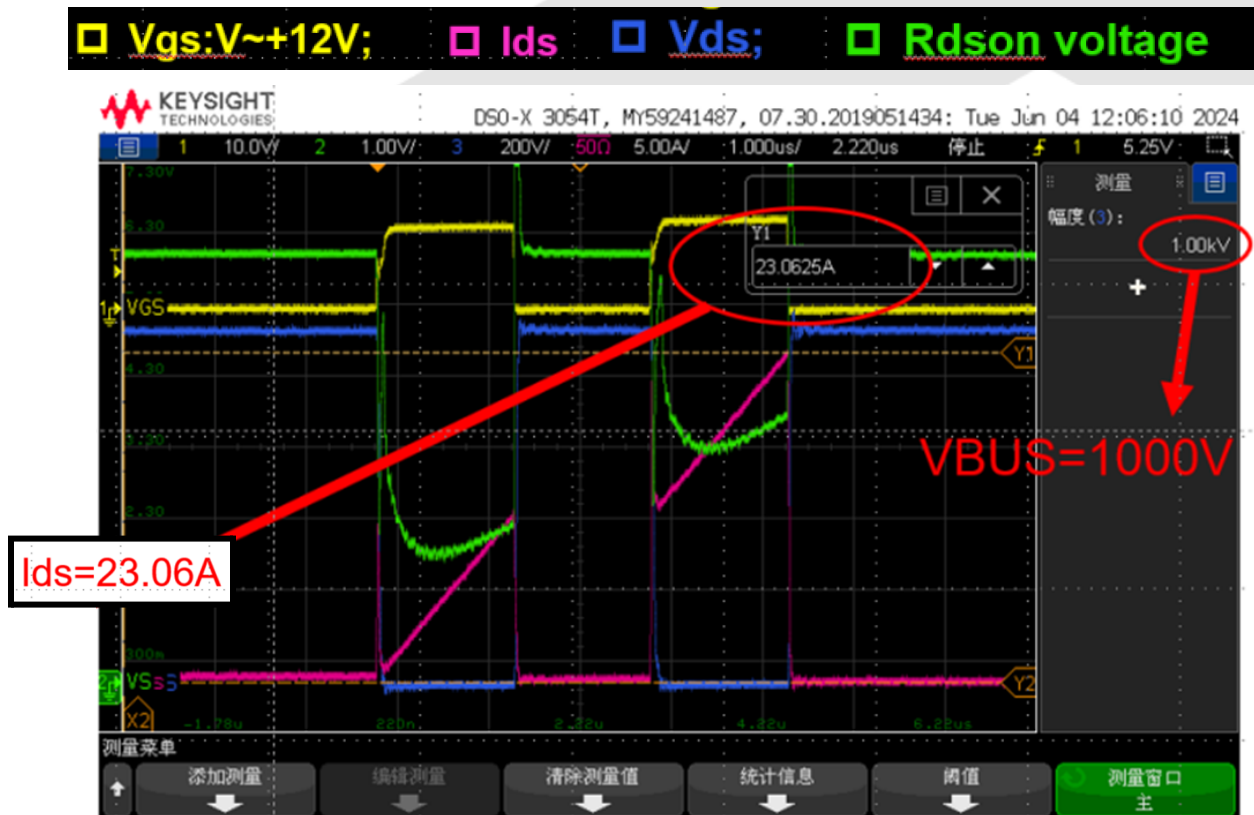
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DPT @ 25°C: $V_{BUS} = 800V$, L-load = 360 μH

Electrical Performance - Dynamic Test



- Double pulse testing using inductance load (L) of 128μH at $V_{BUS} = 1000V$ and $I_{DS} = 23A$
- Clamp diode circuit is used to measure dynamic $R_{DS(on)} = 127m\Omega$

● Switching performance (Inductive load switching)

	Parameters		Conditions	Sample#1	Sample#2	Unit
1	$t_{D(ON)}$	Turn-on delay time	$V_{DS} = 800V$ $I_D = 15A$ $V_{GS} = 0V/12V$	6.40	6.08	ns
2	t_R	Rise time		33.92	30.72	ns
3	$t_{D(OFF)}$	Turn-off delay time		15.36	14.40	ns
4	t_F	Fall time		17.28	16.64	ns
5	E_{ON}	Turn-on energy		182.34	162.26	μJ
6	E_{OFF}	Turn-off energy		84.76	83.37	μJ

Thermal and Soldering Characteristics

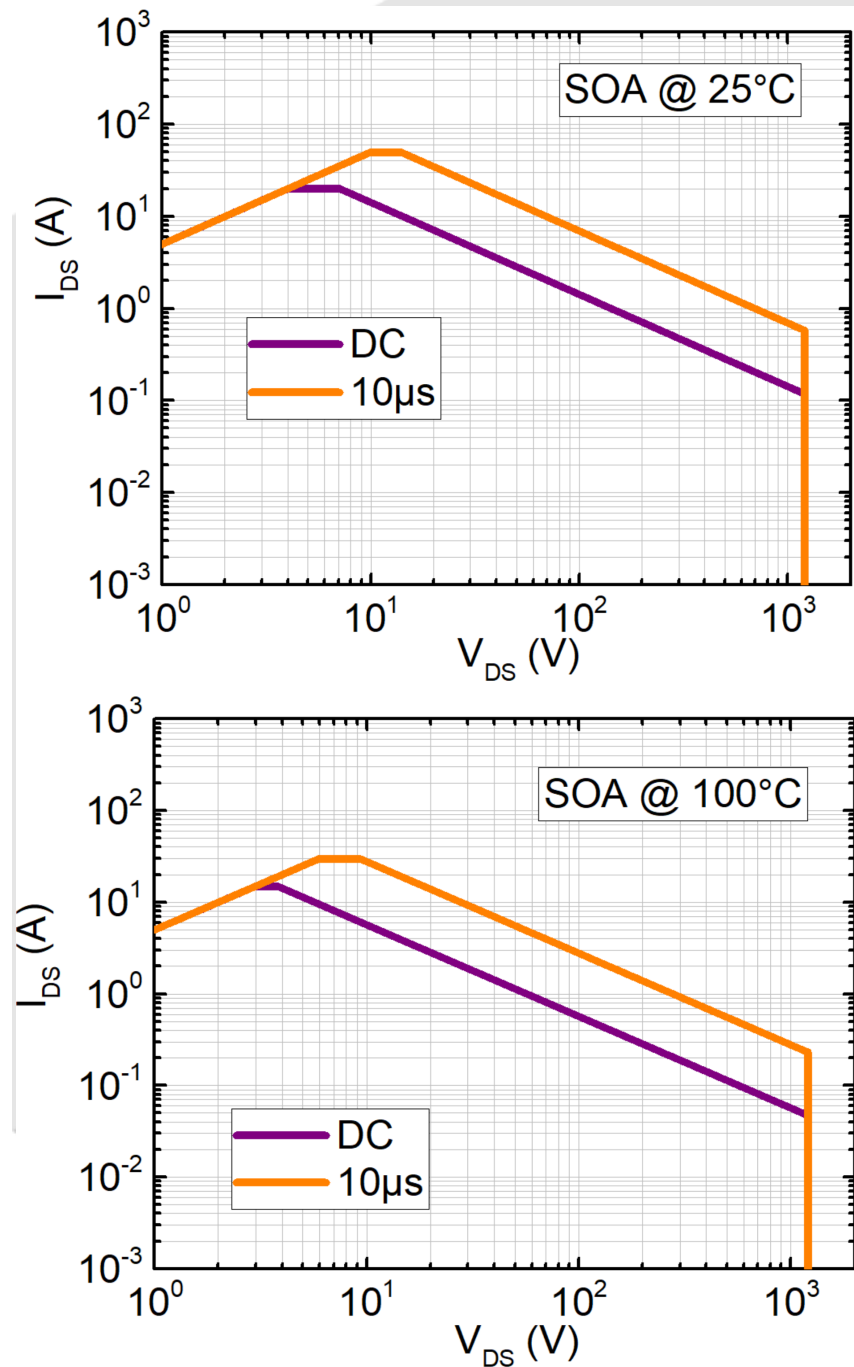
	Symbols	Parameters	Value	Unit	Package
1	R_{thJC}	Thermal resistance (junction to case)	0.6	$^{\circ}C/W$	TO247-4
			0.27		TOLL-3
2	R_{thJA}	Thermal resistance (junction to ambient)	62	$^{\circ}C/W$	TO247-4
			40		TOLL-3
3	T_{solder}	Reflow soldering temperature	260	$^{\circ}C$	All



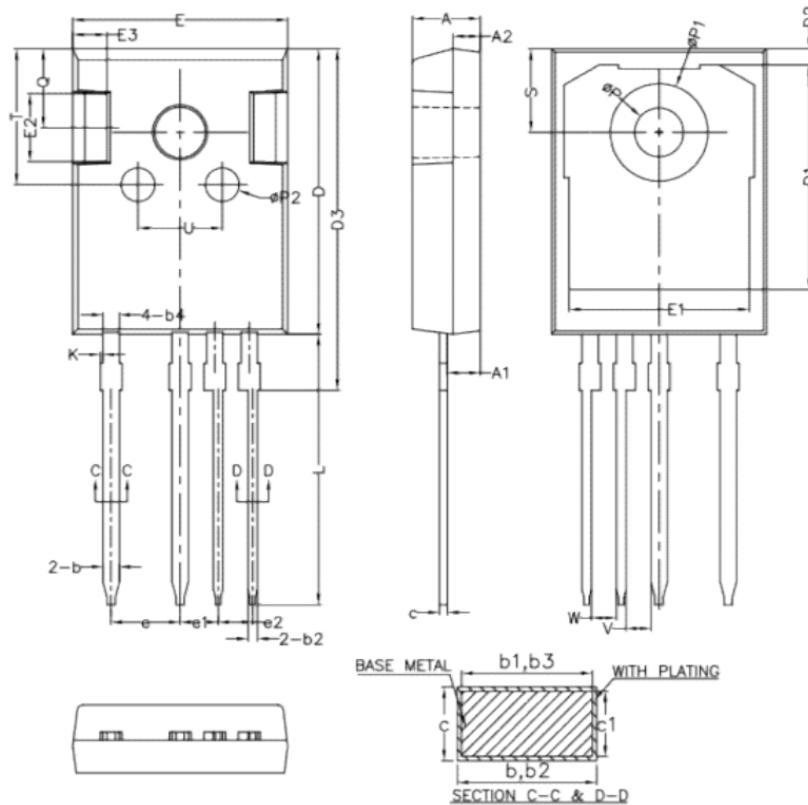
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Safe Operating Area (SOA)



Package Information



SYMBOL	MIN	NOM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16	—	1.29
b1	1.15	1.20	1.25
b2	0.66	—	0.79
b3	0.65	0.70	0.75
b4	1.16	—	1.29
c	0.59	—	0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
D3	24.97	25.12	25.27
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	4.98	5.08	5.18
e1	2.69	2.79	2.89
e2	2.44	2.54	2.64
K	0	—	0.20
L	19.80	19.92	20.10
P	3.50	3.60	3.70
P1	—	—	7.40
P2	2.40	2.50	2.60
Q	5.60	—	6.00
S	6.00	6.15	6.30
T	9.80	—	10.20
U	6.00	—	6.40
V	1.44	1.84	2.24
W	1.44	1.84	2.24

NOTES:
1. ALL DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
2. EJECTION MARK DEPTH $0.10^{+0.15}_{-0.05}$.



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Further Information

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Data Source— Data here are based on recent tests but all parameters may not be up to date. Actual final test data from packaging production are available for selected customers upon request.